



2020 IEEE THE 5TH INTERNATIONAL CONFERENCE ON INTEGRATED CIRCUITS AND MICROSYSTEMS

NANJING, CHINA

ICICM 2020

Introduction

ICICM-International Conference on Integrated Circuits and Microsystems is an annual conference, which aims to provide a platform for researchers, engineers, academicians as well as industrial professionals from all over the world to present their research results and development activities in Integrated Circuits and Microsystems.

The previous 4 editions ICICM were sponsored by IEEE and it has been successfully held in Chengdu on November 23-25, 2016 in Nanjing on November 8-11, 2017, and in Shanghai on November 24-26, 2018, Beijing on October 25-27, 2019. The 5th International Conference on Integrated Circuits and Microsystems (ICICM 2020) will return to Nanjing, China on October 23-25, 2020 with the support from University of Electronic Science and Technology of China and Southeast University, China.

Proceedings

All accepted papers after proper presentation and registration will be collected in the IEEE conference proceedings, which will be submitted and reviewed Ei Compendex, Scopus, and CPCI (Web of Science) after the conference.

- ◆ The proceedings of ICICM2016-2019 have been included in IEEE Xplore and Indexed by Ei Compendex and Scopus.

Committees

| | | |
|--------------------------|----------------------|---|
| Advisory Chairs | ◆ David Z. Pan | The University of Texas at Austin, United States (IEEE Fellow, SPIE Fellow) |
| | ◆ Ljiljana Trajkovic | Simon Fraser University, Canada (IEEE Fellow) |
| Conference Chairs | ◆ Zhigong Wang | Southeast University, China |
| | ◆ Li Qiang | University of Electronic Science and Technology of China, China (Founding Chair of IEEE Chengdu SSCS/CASS Joint Chapter) |
| Program Chairs | ◆ Fei Yuan | Ryerson University, Canada (IET Fellow) |
| | ◆ Zou Zhuo | Fudan University, China |
| | ◆ Liu Dake | Beijing Institute of Technology, China Linköping University, Sweden |
| Steering Committee Chair | ◆ Huang Le Tian | University of Electronic Science and Technology of China, China |

Wechat:



Topics

- ◆ Thz and Microwave MicroSystem
- ◆ Devices and Circuits for Wirless System
- ◆ Application Specific Circuits and Systems for Communication
- ◆ Digital, Analog, Mixed Signal IC and SOC design technology
- ◆ Silicon integrated circuits and manufacturing
- ◆ Low-power, RF devices & circuits
- ◆ IC Computer-Aided –Design technology, DFM
- ◆ Displays, sensors and MEMS
- ◆ Silicon/germanium devices and device physics
- ◆ Packaging and testing technology
- ◆ Organic semiconductor devices and technologies

For more topics, please visit: <http://icim.net/scope.html>

History



ICICM 2019 October 25-27, 2019 | Beijing, China
IEEE Proceedings ISBN: 978-1-7281-5131-1



ICICM 2018 November 24-26, 2018 | Shanghai, China
IEEE Proceedings ISBN: 978-1-5386-8310-1



ICICM 2017 November 8-11, 2017 | Nanjing, China
IEEE Proceedings ISBN: 978-1-5386-3505-6



ICICM 2016 November 23-25, 2016 | Chengdu, China ISBN:
IEEE Proceedings ISBN: 978-1-5090-2813-9

Submission

- ◆ Please log in the EasyChair Submission System (<https://easychair.org/conferences/?conf=icim2020>) and upload your paper
- ◆ Should you have any questions, please feel free to contact us at icim@young.ac.cn
- ◆ Listener can directly download the following registration form and make registration: http://icim.net/files/listener_reg.docx

Important Dates

Submission Deadline **September 15, 2020**

Notification Date **September 30, 2020**

Registration Deadline

For Authors **October 8, 2020**

For Listeners **October 15, 2020**

Sponsored By



Co-Sponsored By



Assisted By



Contact Us

Email: icim@young.ac.cn

Phone: + 86-28-8777577 (service hours are from 10:00 to 18:00 (UTC+08:00) Monday through Friday)